

TCA9517-Q1 レベル変換 I2C バス・リピータ

1 特長

- 車載アプリケーション向けに AEC-Q100 認証済み
 - デバイス温度: $-40^{\circ}\text{C} \sim 125^{\circ}\text{C}$, T_A
 - デバイス HBM 分類レベル: $\pm 5500\text{V}$
 - デバイス CDM 分類レベル: $\pm 1000\text{V}$
- 機能安全対応
 - 機能安全システムの設計に役立つ資料を利用可能
- 2 チャンネルの双方向バッファ
- I²C バスおよび SMBus 互換
- A 側の動作電源電圧範囲: $0.9\text{V} \sim 5.25\text{V}$
- B 側の動作電源電圧範囲: $2.7\text{V} \sim 5.25\text{V}$
- 0.9V から 5.25V へと、 2.7V から 5.25V への電圧レベル変換
- アクティブ HIGH のリピータ・イネーブル入力
- オープン・ドレインの I²C I/O
- 5.25V 許容の I²C およびイネーブル入力で、混在モードの信号動作に対応
- 標準モードおよびファースト・モード I²C デバイスおよび複数のコントローラに対応
- 電源オフ時に I²C ピンが高インピーダンス
- JESD 78, Class II 準拠で 100mA 超のラッチアップ性能

2 アプリケーション

- サーバー
- ルーター (テレコム・スイッチング機器)
- 産業用機器
- 多くの I²C ターゲットや長い PCB 配線を持つ製品

3 概要

TCA9517-Q1 は、I²C および SMBus システム用の、レベル・シフト機能付き双方向バッファです。混在モード・アプリケーションで、低電圧 (最低 0.9V) と、より高い電圧 ($2.7\text{V} \sim 5.25\text{V}$) との間の双方向電圧レベル変換 (昇圧変換 / 降圧変換) を行います。このデバイスにより、I²C および SMBus システムを拡張でき、レベル・シフト時にも性能損失を防ぐことができます。

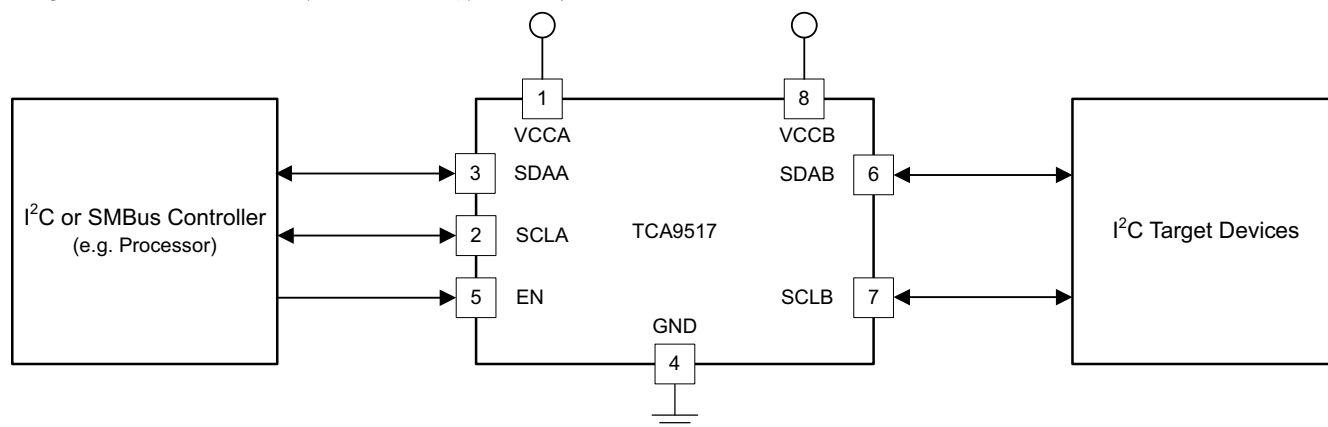
TCA9517-Q1 は、I²C バス上でシリアル・データ (SDA) とシリアル・クロック (SCL) 信号の両方をバッファするため、最大 400pF のバス容量を持つ 2 つのバスを I²C アプリケーション内で接続できます。

TCA9517-Q1 は、2 種類のドライバ (A 側ドライバと B 側ドライバ) を備えています。すべての入力と I/O は、デバイスの電源がオフのとき (V_{CCB} , $V_{CCA} = 0\text{V}$) も含めて、 5.25V までの過電圧を許容します。

製品情報

部品番号	パッケージ ⁽¹⁾	本体サイズ (公称)
TCA9517-Q1	VSSOP (8)	$3.00\text{mm} \times 3.00\text{mm}$

- (1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。



概略回路図



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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision * (June 2018) to Revision A (February 2022)	Page
• すべての古い用語をコントローラおよびターゲットに変更.....	1
• 「特長」に「機能安全対応」を追加.....	1

5 概要 (続き)

B 側のバッファ設計により、静的電圧オフセットを使用するデバイスと直列に使用することが防止されます。このデバイスはバッファされた LOW 信号を有効な LOW とは認識せず、バッファされた LOW として再度伝搬することはありません。

B 側のドライバは、2.7V～5.25V で動作します。この内部バッファの出力 LOW レベルは約 0.5V です。出力が内部で LOW に駆動されるとき、入力電圧は出力 LOW レベルよりも 70mV 以上低い必要があります。より電圧の高い LOW 信号は、バッファされた LOW と呼ばれます。B 側の I/O が内部で LOW に駆動されるとき、この LOW は入力によって LOW と認識されません。この機能により、入力 LOW 条件が解除されたとき、ロックアップ状況が発生することが防止されます。

A 側のドライバは 0.9V～5.25V で動作し、より多くの電流を駆動します。これらのドライバには、バッファされた LOW の機能 (または、静的なオフセット電圧) が必要ありません。B 側の LOW 信号は、A 側ではほぼ 0V の LOW に変換されます。これによって、低電圧のロジックの小さな電圧スイングに対応できます。A 側の出力プルダウンは、ハード LOW を駆動します。この入力レベルは、低電圧側の電源電圧が最低 0.9V のシステムにおいて、低い LOW レベルの要求に対応できるよう、 $0.3 \times V_{CCA}$ に設定されます。

2 つ以上の TCA9517-Q1 デバイスの A 側を互いに接続可能です。これは、A 側を共通バスとした多くの回路形式 (図 8、図 9 を参照) を可能にします。A 側は、静的または動的オフセット電圧を持つその他のすべてのバッファに直接接続できます。複数の TCA9517-Q1 デバイスを A 側から B 側へ直列に接続でき、この場合にオフセット電圧の蓄積はなく、タイム・オブ・フライト遅延のみを考慮すれば十分です。B 側からのバッファされた LOW 電圧の関係で、TCA9517-Q1 を B 側から B 側に接続することはできません。B 側は、立ち上がり時間アクセラレータを持つデバイスには接続できません。

VCCA は、A 側の入力コンパレータに $0.3 \times V_{CCA}$ の基準電圧を供給するためと、パワー・グッド検出回路にのみ使用されます。TCA9517-Q1 のロジックおよびすべての I/O は、VCCB ピンから電力を供給されます。

標準の I²C システムと同様に、バッファされたバスにロジック HIGH レベルを与えるにはプルアップ抵抗が必要です。TCA9517-Q1 は、I²C バスの標準的なオープン・ドレイン構成を持っています。これらのプルアップ抵抗のサイズはシステムに依存しますが、リピータの各側にプルアップ抵抗が必要です。このデバイスは、SMBus デバイスに加えて、標準モードおよびファースト・モードの I²C デバイスとともに動作するよう設計されています。標準モードの I²C デバイスは、一般的な I²C システムで 3mA のみが規定されており、標準モード・デバイスと複数のマスタを使用可能です。場合によっては、より大きな終端電流を使用できます。

6 Pin Configuration and Functions

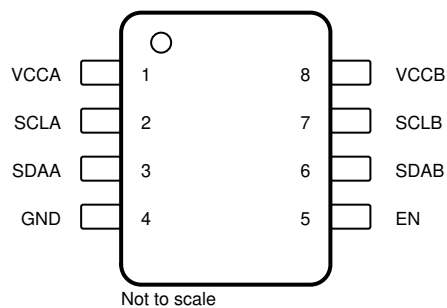


图 6-1. DGK (VSSOP) Package, 8-Pin, Top View

表 6-1. Pin Functions

PIN		TYPE	DESCRIPTION
NO.	NAME		
1	VCCA	Supply	A-side supply voltage (0.9 V to 5.25 V)
2	SCLA	Input/Output	Serial clock bus, A-side. Connect to V_{CCA} through a pull-up resistor. If unused, connect directly to ground.
3	SDAA	Input/Output	Serial data bus, A-side. Connect to V_{CCA} through a pull-up resistor. If unused, connect directly to ground.
4	GND	Ground	Ground
5	EN	Input	Active-high repeater enable input
6	SDAB	Input/Output	Serial data bus, B-side. Connect to V_{CCB} through a pull-up resistor. If unused, connect directly to ground.
7	SCLB	Input/Output	Serial clock bus, B-side. Connect to V_{CCB} through a pull-up resistor. If unused, connect directly to ground.
8	VCCB	Supply	B-side and device supply voltage (2.7 V to 5.25 V)

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CCB}	Supply voltage range	–0.5	7	V
V _{CCA}	Supply voltage range	–0.5	7	V
V _I	Enable input voltage range ⁽²⁾	–0.5	7	V
V _{I/O}	I ² C bus voltage range ⁽²⁾	–0.5	7	V
I _{IK}	Input clamp current	V _I < 0 V _O < 0	–50	mA
I _{OK}	Output clamp current		–50	
I _O	Continuous output current		±50	mA
	Continuous current through V _{CC} or GND		±100	mA
T _{stg}	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

7.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±5500
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000
		Machine model (A115-A)	±200

- (1) JEDEC document JEP155 states that 500 V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250 V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CCA}	Supply voltage, A-side bus	0.9 ⁽²⁾	5.25	V
V _{CCB}	Supply voltage, B-side bus	V _{CCA} ≤ V _{CCB}	2.7	V
		V _{CCA} > V _{CCB}	2.9	
V _{IH}	High-level input voltage	SDAA, SCLA	0.7 × V _{CCA}	V
		SDAB, SCLB	0.7 × V _{CCB}	
		EN	0.7 × V _{CCB}	
V _{IL}	Low-level input voltage	SDAA, SCLA	0.3 × V _{CCA}	V
		SDAB, SCLB ⁽¹⁾	0.3 × V _{CCB}	
		EN	0.3 × V _{CCB}	
I _{OL}	Low-level output current		6	mA
T _A	Operating free-air temperature	–40	125	°C

- (1) V_{IL} specification is for the first low level seen by the SDAB and SCLB lines. V_{ILC} is for the second and subsequent low levels seen by the SDAB and SCLB lines. See セクション 10.2.2.2 for V_{ILC} application information
- (2) Low-level supply voltage

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TCA9517-Q1	UNIT
		DGK (VSSOP)	
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	187.6	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	59.3	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	108.6	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	3.4	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	106.9	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.5 Electrical Characteristics

 $V_{CCB} = 2.7\text{ V to }5.25\text{ V}$, $GND = 0\text{ V}$, $T_A = -40^\circ\text{C to }125^\circ\text{C}$ (unless otherwise noted)

PARAMETER			TEST CONDITIONS	V _{CCB}	MIN	TYP	MAX	UNIT
V _{IK}	Input clamp voltage		I _I = −18 mA	2.7 V to 5.25 V			−1.2	V
V _{OL}	Low-level output voltage	SDAB, SCLB	I _{OL} = 100 μA or 6 mA, V _{ILA} = V _{ILB} = 0 V	2.7 V to 5.25 V	0.45	0.52	0.6	V
		SDAA, SCLA	I _{OL} = 6 mA			0.1	0.2	
V _{OL} − V _{ILC}	Low-level input voltage below low-level output voltage	SDAB, SCLB	ensured by design	2.7 V to 5.25 V		70		mV
V _{ILC}	SDA and SCL low-level input voltage contention	SDAB, SCLB		2.7 V to 5.25 V		0.4		V
I _{CC}	Quiescent supply current for V _{CCA}		Both channels low, SDAA = SCLA = GND and SDAB = SCLB = open, or SDAA = SCLA = open and SDAB = SCLB = GND				1	mA
I _{CC}	Quiescent supply current		Both channels high, SDAA = SCLA = V _{CCA} and SDAB = SCLB = V _{CCB} and EN = V _{CCB}	5.25 V		1.5	5	mA
			Both channels low, SDAA = SCLA = GND and SDAB = SCLB = open			1.5	5	
			In contention, SDAA = SCLA = GND and SDAB = SCLB = GND			3	5	
I _I	Input leakage current	SDAB, SCLB	V _I = V _{CCB}	2.7 V to 5.25 V			±1	μA
			V _I = 0.2 V				10	
		SDAA, SCLA	V _I = V _{CCB}				±1	
			V _I = 0.2 V				10	
		EN	V _I = V _{CCB}				±1	
			V _I = 0.2 V			−10	−30	
I _{OH}	High-level output leakage current	SDAB, SCLB	V _O = 3.6 V	2.7 V to 5.25 V		10	μA	
		SDAA, SCLA				10		
C _I	Input capacitance	EN	V _I = 3 V or 0 V	3.3 V		6	10	pF
		SCLA, SCLB	V _I = 3 V or 0 V	3.3 V		8	13	
				0 V		7	11	
C _{IO}	Input/output capacitance	SDAA, SDAB	V _I = 3 V or 0 V	3.3 V		8	13	pF
						0 V		

7.6 Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
t_{su} Setup time, EN high before Start condition ⁽¹⁾	100		ns
t_h Hold time, EN high after Stop condition ⁽¹⁾	100		ns

⁽¹⁾ EN should change state only when the global bus and the repeater port are in an idle state.

7.7 I²C Interface Switching Characteristics

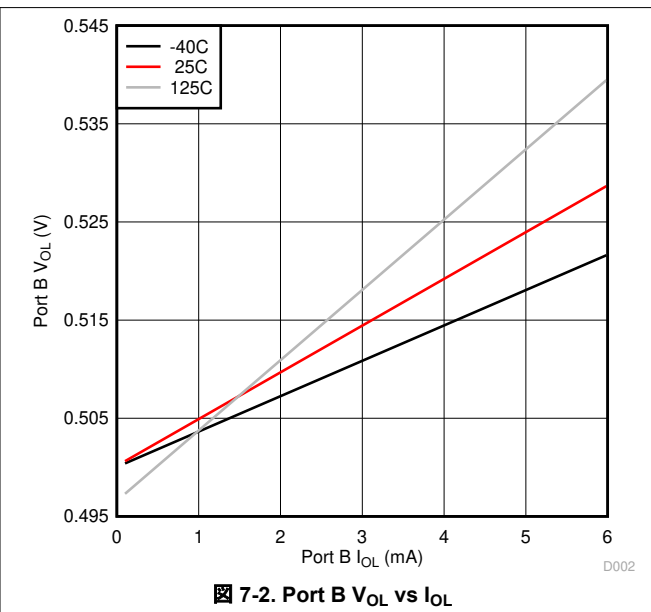
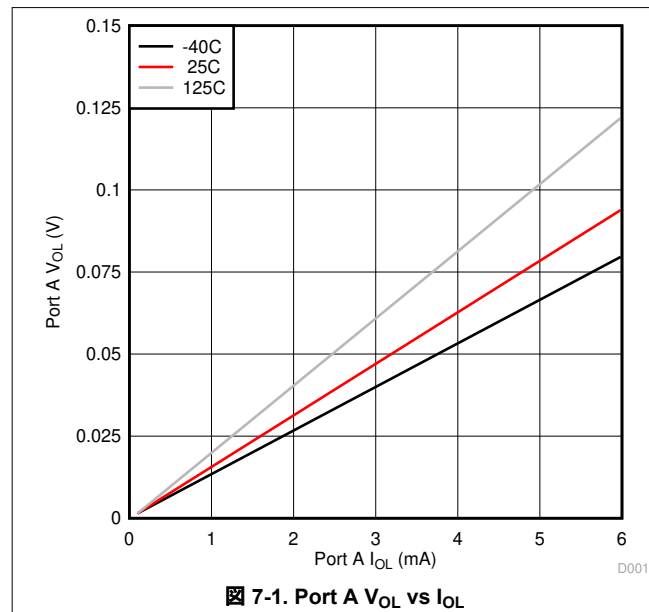
$V_{CCB} = 2.7\text{ V to } 5.25\text{ V}$, $GND = 0\text{ V}$, $T_A = -40^\circ\text{C to } 125^\circ\text{C}$ (unless otherwise noted)^{(1) (4)}

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP ⁽⁵⁾	MAX	UNIT
t_{PLZ}	Propagation delay	SDAB, SCLB ⁽³⁾ (see 8-4)	SDAA, SCLA ⁽³⁾ (see 8-4)			141	250	ns
		SDAA, SCLA ⁽²⁾ (see 8-3)	SDAB, SCLB ⁽²⁾ (see 8-3)			74	110	
t_{PZL}	Propagation delay	SDAB, SCLB	SDAA, SCLA	$V_{CCA} \leq 2.7\text{ V}$ (see 8-2)		76 ⁽⁶⁾	110	ns
				$V_{CCA} \geq 3\text{ V}$ (see 8-2)		95	290	
		SDAA, SCLA ⁽²⁾ (see 8-3)	SDAB, SCLB ⁽²⁾ (see 8-3)			107	230	
t_{TLH}	Transition time	80%	20%	$V_{CCA} \leq 2.7\text{ V}$ (see 8-3)		12		ns
				$V_{CCA} \geq 3\text{ V}$ (see 8-3)		42		
						125		
t_{THL}	Transition time	80%	20%	$V_{CCA} \leq 2.7\text{ V}$ (see 8-3)		67 ⁽⁶⁾	200	ns
				$V_{CCA} \geq 3\text{ V}$ (see 8-3)		86	240	
						48	120	

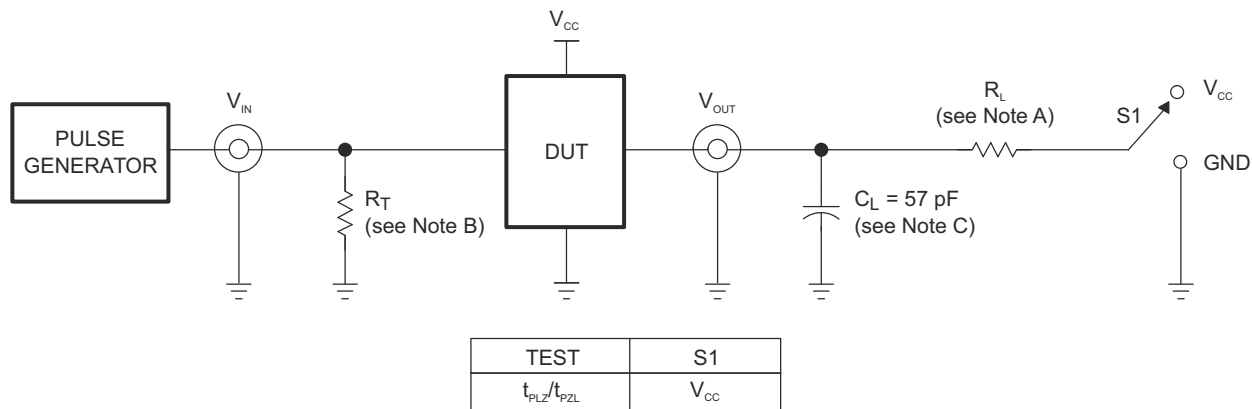
- (1) Times are specified with loads of 1.35-k Ω pull-up resistance and 50-pF load capacitance on the B-side. On the A side, for $0.9\text{ V} \leq V_{CCA} \leq 2.7\text{ V}$, a 167- Ω pull-up and 57-pF load capacitance. For $V_{CCA} \geq 3.0\text{ V}$, a 450- Ω pull-up and 57-pF load capacitance. Different load resistance and capacitance alter the RC time constant, thereby changing the propagation delay and transition times.
- (2) The proportional delay data from A to B-side is measured at 0.3 V_{CCA} on the A side to 1.5 V on the B-side.
- (3) The t_{PLH} delay data from B to A side is measured at 0.4 V on the B-side to 0.5 V_{CCA} on the A side when V_{CCA} is less than 2 V, and 1.5 V on the A side if V_{CCA} is greater than 2 V.
- (4) pull-up voltages are V_{CCA} on the A side and V_{CCB} on the B-side.
- (5) Typical values were measured with $V_{CCA} = V_{CCB} = 3.3\text{ V}$ at $T_A = 25^\circ\text{C}$, unless otherwise noted.
- (6) Typical value measured with $V_{CCA} = 2.7\text{ V}$ at $T_A = 25^\circ\text{C}$

7.8 Typical Characteristics

$V_{CCA} = 0.9\text{ V}$, $V_{CCB} = 2.7\text{ V}$



8 Parameter Measurement Information

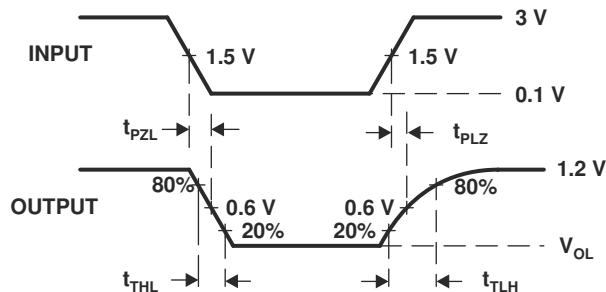


TEST CIRCUIT FOR OPEN-DRAIN OUTPUT

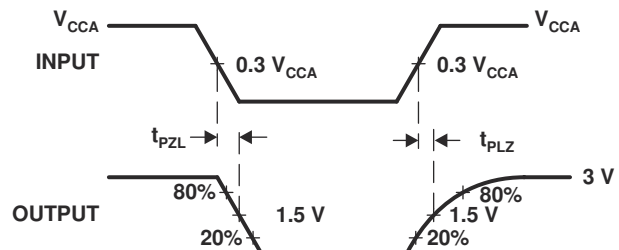
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- A. $R_L = 167\ \Omega$ (0.9 V to 2.7 V) and $R_L = 450\ \Omega$ (3.0 V to 5.25 V) on the A side and 1.35 k Ω on the B-side
- B. R_T termination resistance should be equal to Z_{OUT} of pulse generators.
- C. C_L includes probe and jig capacitance. $C_L = 50\text{ pF}$ when on the B-side.
- D. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, slew rate $\geq 1\text{ V/ns}$.
- E. The outputs are measured one at a time, with one transition per measurement.
- F. t_{PLH} and t_{PHL} are the same as t_{pd} .
- G. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- H. t_{PZL} and t_{PZH} are the same as t_{en} .

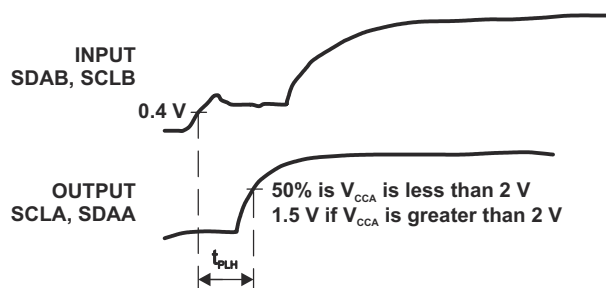
8-1. Test Circuit



8-2. Waveform 1 – Propagation Delay and Transition Times for B-side to A-side



8-3. Waveform 2 – Propagation Delay and Transition Times for A-side to B-side



8-4. Waveform 3 – Propagation Delay for B-side to A-side

9 Detailed Description

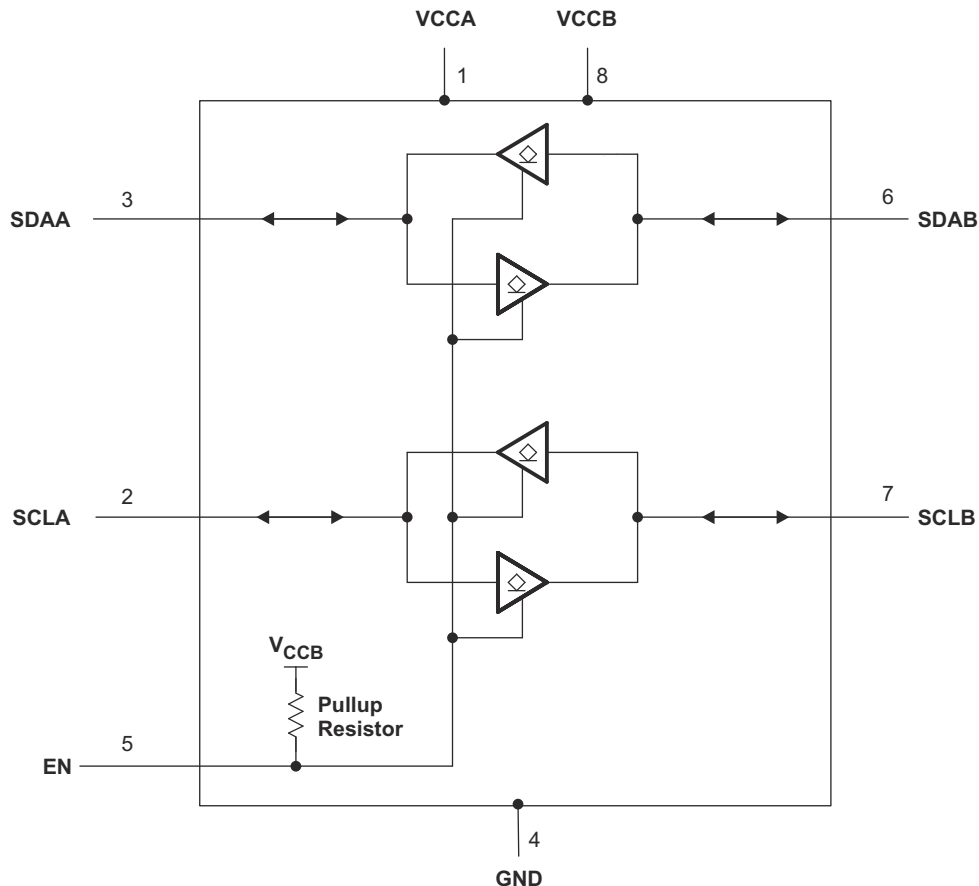
9.1 Overview

The TCA9517-Q1 is a bidirectional buffer with level shifting capabilities for I²C and SMBus systems. It provides bidirectional voltage-level translation (up-translation/down-translation) between low voltages (down to 0.9 V) and higher voltages (2.7 V to 5.25 V) in mixed-mode applications. This device enables I²C and SMBus systems to be extended without degradation of performance, even during level shifting.

The TCA9517-Q1 buffers both the serial data (SDA) and the serial clock (SCL) signals on the I²C bus, thus allowing two buses of up to 400-pF bus capacitance to be connected in an I²C application.

The TCA9517-Q1 has two types of drivers: A-side drivers and B-side drivers. All inputs and I/Os are over-voltage tolerant to 5.25 V, even when the device is unpowered (V_{CCB} and/or $V_{CCA} = 0$ V).

9.2 Functional Block Diagram



9.3 Feature Description

9.3.1 Two-Channel Bidirectional Buffer

The TCA9517-Q1 is a two-channel bidirectional buffer with level-shifting capabilities

9.3.2 Active-High Repeater-Enable Input

The TCA9517-Q1 has an active-high enable (EN) input with an internal pull-up to V_{CCB} , which allows the user to select when the repeater is active. This can be used to isolate a badly behaved target on power-up reset. The EN input should change state only when the global bus and repeater port are in an idle state, to prevent system failures.

9.3.3 V_{OL} B-Side Offset Voltage

The B-side drivers operate from 2.7 V to 5.25 V. The output low level for this internal buffer is approximately 0.5 V, but the input voltage must be 70 mV or more below the output low level when the output internally is driven low. The higher-voltage low signal is called a buffered low. When the B-side I/O is driven low internally, the low is not recognized as a low by the input. This feature prevents a lockup condition from occurring when the input low condition is released. This type of design prevents 2 B-side ports from being connected to each other.

9.3.4 Standard Mode and Fast Mode Support

The TCA9517-Q1 supports standard mode as well as fast mode I²C. The maximum system operating frequency will depend on system design and the delays added by the repeater.

9.3.5 Clock Stretching Support

The TCA9517-Q1 can support clock stretching, but care needs to be taken to minimize the overshoot voltage presented during the hand-off between the target and controller. This is best done by increasing the pull-up resistor value.

9.4 Device Functional Modes

表 9-1. Function Table

INPUT EN	FUNCTION
L	Outputs disabled
H	SDAA = SDAB SCLA = SCLB

10 Application and Implementation

Note

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10.1 Application Information

A typical application is shown in [Figure 10-1](#). In this example, the system controller is running on a 3.3 V I²C bus, and the target is connected to a 1.2 V I²C bus. Both buses run at 400 kHz. Controller devices can be placed on either bus.

The TCA9517-Q1 is 5-V tolerant, so it does not require any additional circuitry to translate between 0.9 V to 5.25 V bus voltages and 2.7 V to 5.25 V bus voltages.

When the A side of the TCA9517-Q1 is pulled low by a driver on the I²C bus, a comparator detects the falling edge when it goes below $0.3 \times V_{CCA}$ and causes the internal driver on the B-side to turn on, causing the B-side to pull down to about 0.5 V. When the B-side of the TCA9517-Q1 falls, first a CMOS hysteresis-type input detects the falling edge and causes the internal driver on the A side to turn on and pull the A-side pin down to ground. In order to illustrate what would be seen in a typical application, refer to [Figure 10-3](#) and [Figure 10-4](#). If the bus controller in [Figure 10-1](#) were to write to the target through the TCA9517-Q1, waveforms shown in [Figure 10-3](#) would be observed on the A bus. This looks like a normal I²C transmission, except that the high level may be as low as 0.9 V, and the turn on and turn off of the acknowledge signals are slightly delayed.

On the B-side bus of the TCA9517-Q1, the clock and data lines would have a positive offset from ground equal to the V_{OL} of the TCA9517-Q1. After the eighth clock pulse, the data line is pulled to the V_{OL} of the target device, which is very close to ground in this example. At the end of the acknowledge, the level rises only to the low level set by the driver in the TCA9517-Q1 for a short delay, while the A-bus side rises above $0.3 \times V_{CCA}$ and then continues high.

10.2 Typical Application

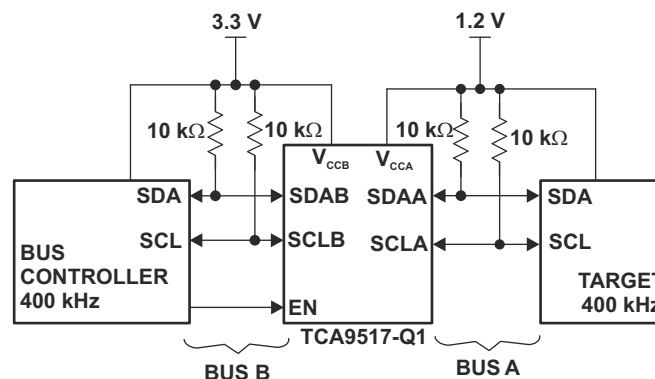


Figure 10-1. Typical Application Schematic

10.2.1 Design Requirements

For the level translating application, the following should be true:

- $V_{CCA} = 0.9 \text{ V to } 5.25 \text{ V}$
- $V_{CCB} = 2.7 \text{ to } 5.25 \text{ V}$
- B-side ports must not be connected together

10.2.2 Detailed Design Procedure

10.2.2.1 Clock Stretching Support

The TCA9517-Q1 can support clock stretching, but care needs to be taken to minimize the overshoot voltage presented during the hand-off between the target and controller. This is best done by increasing the pull-up resistor value.

10.2.2.2 V_{ILC} and Pullup Resistor Sizing

For the TCA9517-Q1 to function correctly, all devices on the B-side must be able to pull the B-side below the voltage input low contention level (V_{ILC}). This means that the V_{OL} of any device on the B-side must be below 0.4 V.

V_{OL} of a device can be adjusted by changing the I_{OL} through the device which is set by the pull-up resistance value. The pull-up resistance on the B-side must be carefully selected to ensure that logic levels will be transferred correctly to the A-side.

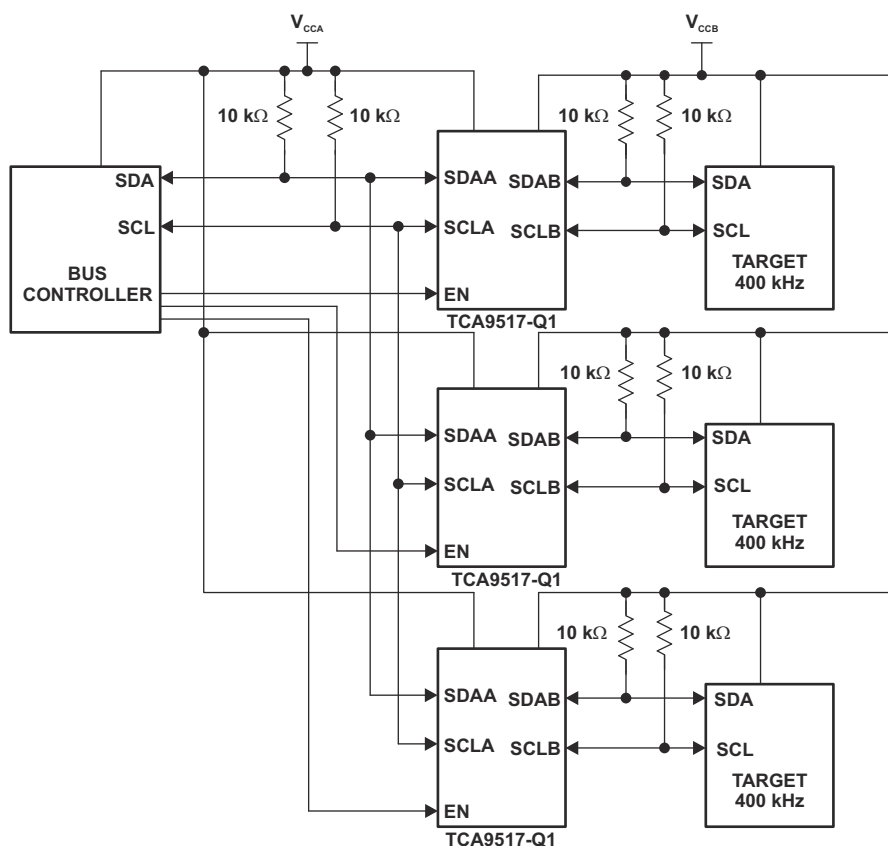


FIG 10-2. Typical Star Application

Multiple A sides of TCA9517-Q1s can be connected in a star configuration, allowing all nodes to communicate with each other.

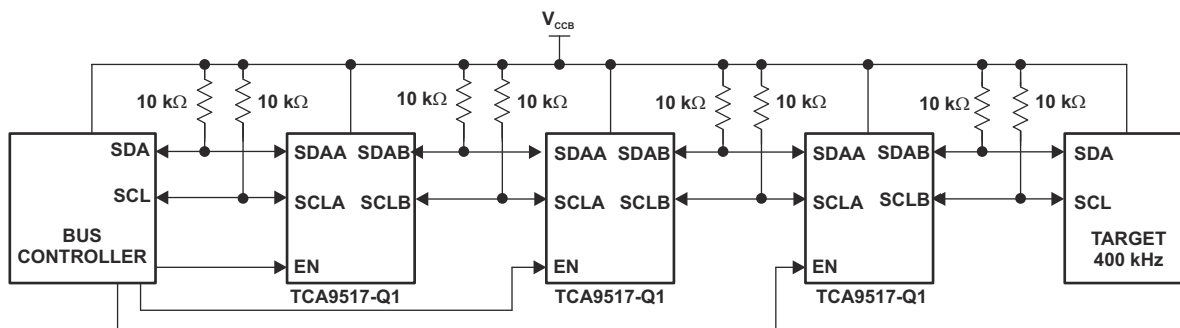


Figure 10-3. Typical Series Application

To further extend the I²C bus for long traces/cables, multiple TCA9517-Q1s can be connected in series as long as the A-side is connected to the B-side. I²C bus target devices can be connected to any of the bus segments. The number of devices that can be connected in series is limited by repeater delay/time-of-flight considerations on the maximum bus speed requirements.

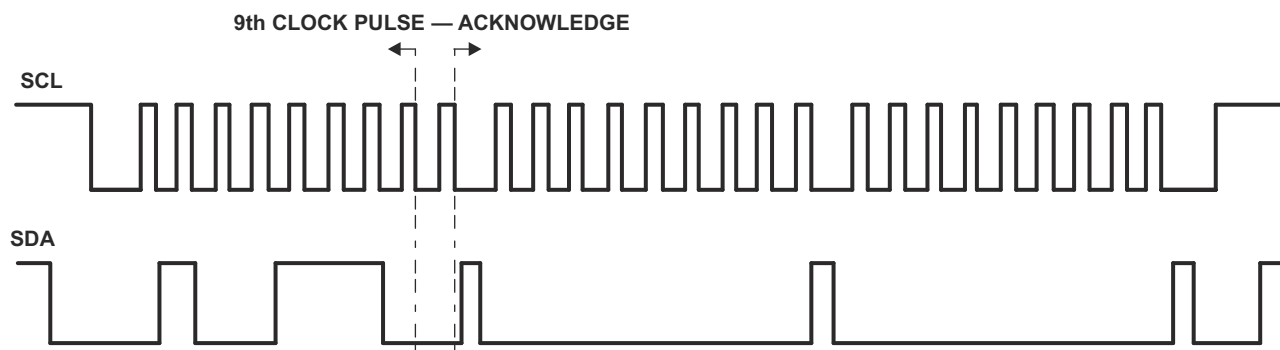


Figure 10-4. Bus A (0.9 V to 5.25 V Bus) Waveform

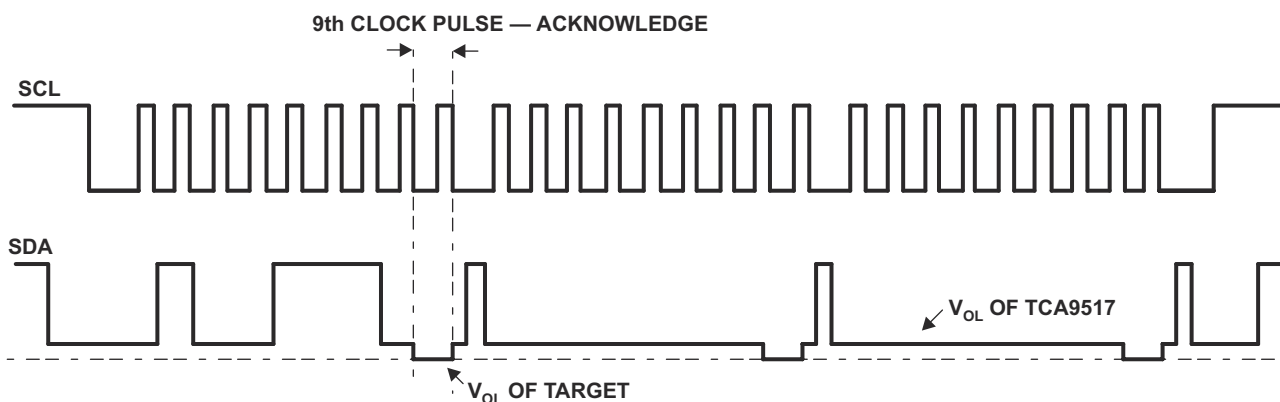
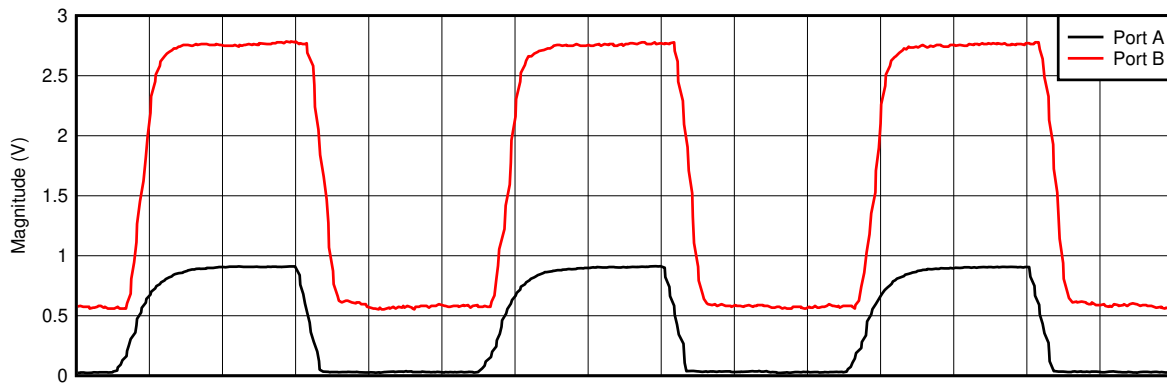


Figure 10-5. Bus B (2.7 V to 5.25 V Bus) Waveform

10.2.3 Application Curve



D003

10-6. Voltage Translation at 400 kHz, $V_{CCA} = 0.9\text{ V}$, $V_{CCB} = 2.7\text{ V}$

11 Power Supply Recommendations

V_{CCB} and V_{CCA} can be applied in any sequence at power up. The TCA9517-Q1 includes a power-up circuit that keeps the output drivers turned off until V_{CCB} is above 2.5 V and the V_{CCA} is above 0.8 V. After power up and with the EN high, a low level on the A-side (below $0.3 \times V_{CCA}$) turns the corresponding B-side driver (either SDA or SCL) on and drives the B-side down to approximately 0.5 V. When the A-side rises above $0.3 \times V_{CCA}$, the B-side pull-down driver is turned off and the external pull-up resistor pulls the pin high. When the B-side falls first and goes below $0.3 \times V_{CCB}$, the A-side driver is turned on and the A-side pulls down to 0 V. The B-side pull-down is not enabled unless the B-side voltage goes below 0.4 V. If the B-side low voltage does not go below 0.5 V, the A-side driver turns off when the B-side voltage is above $0.7 \times V_{CCB}$. If the B-side low voltage goes below 0.4 V, the B-side pull-down driver is enabled, and the B-side is able to rise to only 0.5 V until the A-side rises above $0.3 \times V_{CCA}$.

TI recommends using a decoupling capacitor and placing it close to the VCCA and VCCB pins of a value of about 100 nF.

12 Layout

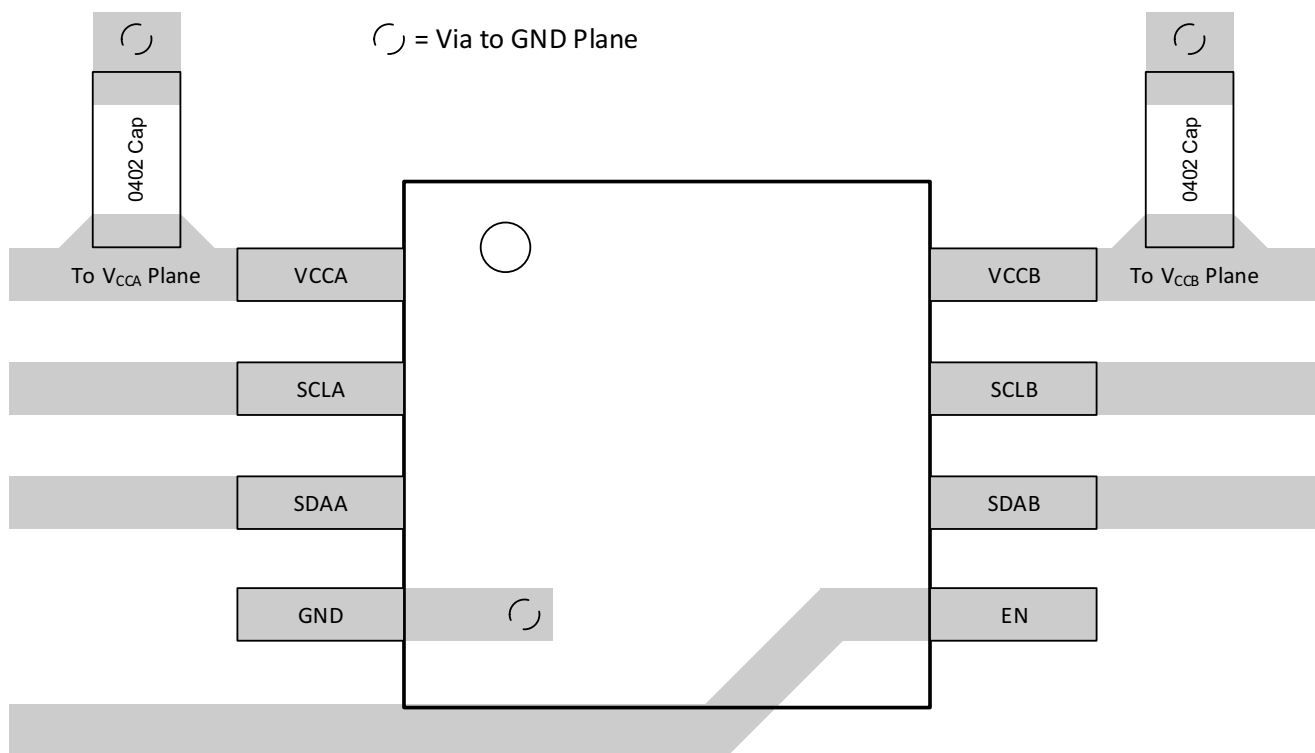
12.1 Layout Guidelines

There are no special layout procedures required for the TCA9517-Q1.

It is recommended that the decoupling capacitors be placed as close to the VCC pins as possible.

12.2 Layout Example

☒ 12-1 shows an example layout of the DGK package.



☒ 12-1. TCA9517-Q1A Layout Example

13 Device and Documentation Support

13.1 Device Support

13.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

13.3 サポート・リソース

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13.4 Trademarks

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13.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

13.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TCA9517DGKRQ1	ACTIVE	VSSOP	DGK	8	2500	RoHS & Green	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	1N2	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF TCA9517-Q1 :

- Catalog : [TCA9517](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TCA9517DGKRQ1	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

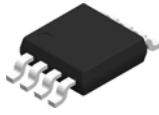
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

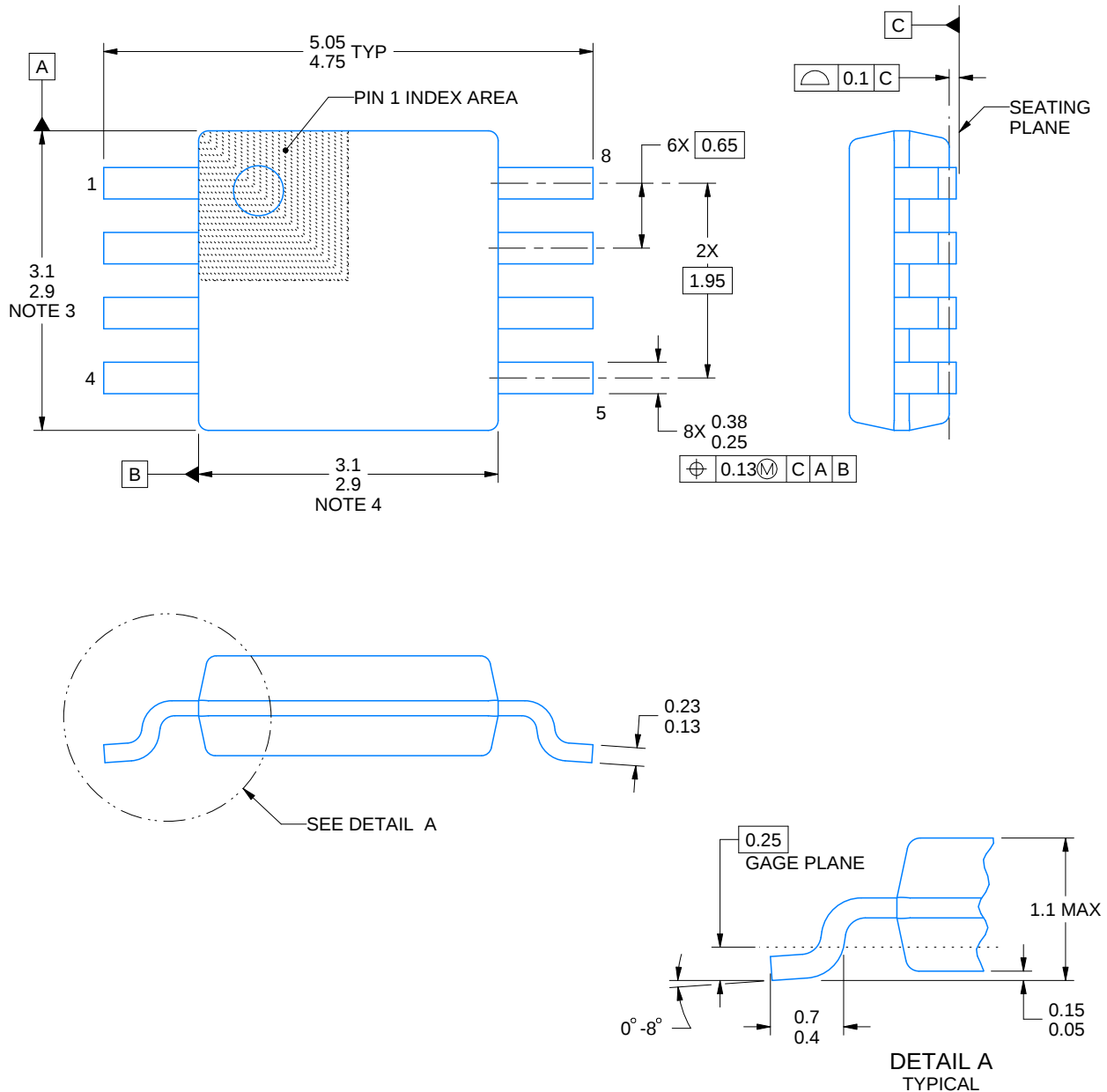
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TCA9517DGKRQ1	VSSOP	DGK	8	2500	366.0	364.0	50.0

DGK0008A



PACKAGE OUTLINE
VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



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NOTES:

PowerPAD is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

EXAMPLE BOARD LAYOUT

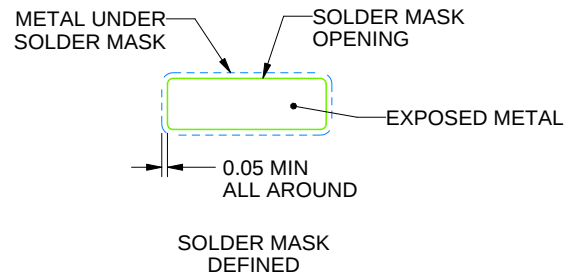
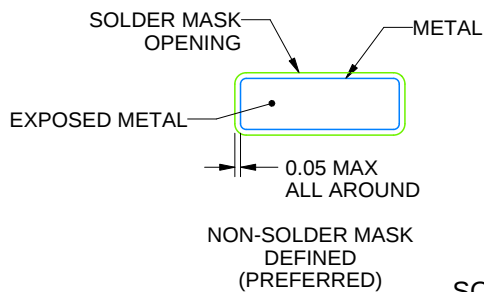
DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X



SOLDER MASK DETAILS

4214862/A 04/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
SCALE: 15X

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NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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